Product Change Notification: BLAS-18SBIW618

Date:

25-Feb-2026

Product Category:

Linear Comparators, Linear Op Amps, Linear Regulators

Notification Subject:

CCB 8081 Final Notice: Qualification of CuPdAu as a new bond wire material for selected MCP1726, MCP621, MCP622, MCP631, MCP632, MCP633, MCP651, MCP652, MCP6562, MCP6567, MCP661, MCP662, MCP663, MCP6V01, MCP6V02, MCP6V03, MCP6V06, MCP6V07, MCP6V08, MCP6V26, MCP6V27, MCP6V28, TC1107, TC1173, TC1174, TC1263 and TC1265 device families available in 8L SOIC (.150in) package assembled at MTAI site.

Affected CPNs:

BLAS-18SBIW618_Affected_CPN_02252026.pdf
BLAS-18SBIW618_Affected_CPN_02252026.csv

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of CuPdAu as a new bond wire material for selected MCP1726, MCP621, MCP622, MCP631, MCP632, MCP633, MCP651, MCP652, MCP6562, MCP6567, MCP661, MCP662, MCP663, MCP6V01, MCP6V02, MCP6V03, MCP6V06, MCP6V07, MCP6V08, MCP6V26, MCP6V27, MCP6V28, TC1107, TC1173, TC1174, TC1263 and TC1265 device families available in 8L SOIC (.150in) package assembled at MTAI site.

Pre and Post Summary Changes:

	Pre Change	**Post Change**
Assembly Site	Microchip Technology Thailand (HQ) (MTAI)	Microchip Technology Thailand

				(HQ) (MTAI)	
Wire Material	Au			CuPdAu	
Die Attach Material	8390A			8390A	
Molding Compound Material	G600V			G600V	
Lead-Frame Material	CDA194			CDA194	
Lead-Frame Paddle Size	60 x 60 mils	90 x 90 mils	95 x158 mils	90 x 90 mils	95 x 130 mils
DAP Surface Prep	Ag Bare Cu			Bare Cu	

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve manufacturability by qualifying CuPdAu as a new bond wire material.

Change Implementation Status: In Progress

Estimated First Ship Date: 12 April 2026 (date code: 2615)

Note Below EFSD: Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Timetable Summary:

	February 2026				>	**April 2026**				
Work Week	06	07	08	09		14	15	16	17	18
Qual Report Availability				X						
Final PCN Issue Date				X						
Estimated Implementation Date								X		

Method to Identify Change: Traceability Code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History: February 25, 2026: Issued initial notification.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

PCN_BLAS-18SBIW618 Qual Report RevA.pdf

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

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